



August 2015

# FCPF2250N80Z

## N-Channel SuperFET<sup>®</sup> II MOSFET

800 V, 3.5 A, 2.25 Ω

### Features

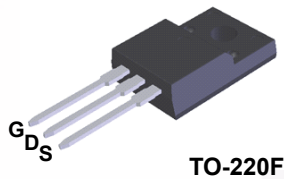
- $R_{DS(on)} = 1.8 \Omega$  (Typ.)
- Ultra Low Gate Charge (Typ.  $Q_g = 11 \text{ nC}$ )
- Low  $E_{oss}$  (Typ.  $1.1 \mu\text{J @ 400V}$ )
- Low Effective Output Capacitance (Typ.  $C_{oss(eff.)} = 51 \text{ pF}$ )
- 100% Avalanche Tested
- RoHS Compliant
- ESD Improved Capability

### Applications

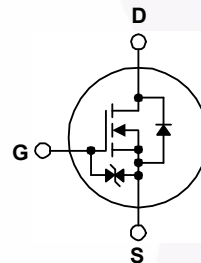
- AC - DC Power Supply
- LED Lighting

### Description

SuperFET<sup>®</sup> II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance,  $dv/dt$  rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as Audio, Laptop adapter, Lighting, ATX power and industrial power applications.



TO-220F



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	FCPF2250N80Z	Unit
$V_{DSS}$	Drain to Source Voltage	800	V
$V_{GSS}$	Gate to Source Voltage	- DC	$\pm 20$
		- AC ( $f > 1 \text{ Hz}$ )	$\pm 30$
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ )	3.5*
		- Continuous ( $T_C = 100^\circ\text{C}$ )	2.2*
$I_{DM}$	Drain Current	- Pulsed (Note 1)	6.5*
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	21.6	mJ
$I_{AR}$	Avalanche Current (Note 1)	0.52	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	0.22	mJ
$dv/dt$	MOSFET $dv/dt$	100	V/ns
	Peak Diode Recovery $dv/dt$ (Note 3)	20	
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	21.9
		- Derate Above $25^\circ\text{C}$	0.18
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

\*Drain current limited by maximum junction temperature, with heatsink.

### Thermal Characteristics

Symbol	Parameter	FCPF2250N80Z	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	5.7	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCPF2250N80Z	FCPF2250N80Z	TO-220F	Tube	N/A	N/A	50 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}, T_J = 25^\circ\text{C}$	800	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{ mA}$ , Referenced to $25^\circ\text{C}$	-	0.85	-	V/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 800\text{ V}, V_{GS} = 0\text{ V}$	-	-	25	$\mu\text{A}$
		$V_{DS} = 640\text{ V}, V_{GS} = 0\text{ V}, T_C = 125^\circ\text{C}$	-	-	250	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 10$	$\mu\text{A}$

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 0.26\text{ mA}$	2.5	-	4.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 1.3\text{ A}$	-	1.8	2.25	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 20\text{ V}, I_D = 1.3\text{ A}$	-	2.28	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	-	440	585	pF
$C_{oss}$	Output Capacitance		-	16	22	pF
$C_{rss}$	Reverse Transfer Capacitance		-	0.75	-	pF
$C_{oss}$	Output Capacitance	$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	-	8.4	-	pF
$C_{oss(eff.)}$	Effective Output Capacitance	$V_{DS} = 0\text{ V to } 480\text{ V}, V_{GS} = 0\text{ V}$	-	51	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 640\text{ V}, I_D = 2.6\text{ A}, V_{GS} = 10\text{ V}$	-	11	14	nC
$Q_{gs}$	Gate to Source Gate Charge		-	2.2	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		(Note 4)	-	4.3	-
ESR	Equivalent Series Resistance	$f = 1\text{ MHz}$	-	2.8	-	$\Omega$

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 400\text{ V}, I_D = 2.6\text{ A}, V_{GS} = 10\text{ V}, R_g = 4.7\text{ }\Omega$	-	11	32	ns
$t_r$	Turn-On Rise Time		-	6.7	23	ns
$t_{d(off)}$	Turn-Off Delay Time		-	26	62	ns
$t_f$	Turn-Off Fall Time		(Note 4)	-	8.7	27

### Drain-Source Diode Characteristics

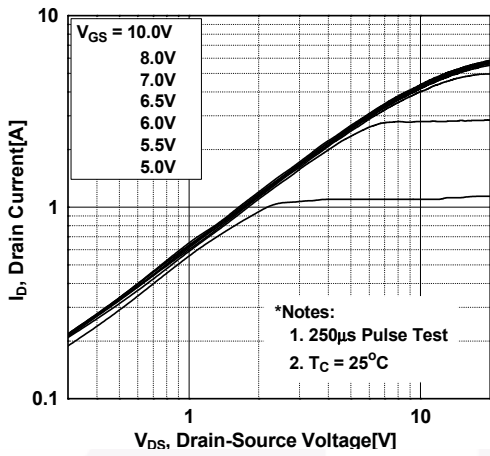
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	3.5	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	6.5	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_{SD} = 2.6\text{ A}$	-	-	1.2	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_{SD} = 2.6\text{ A}, di_F/dt = 100\text{ A}/\mu\text{s}$	-	260	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	2.2	-	$\mu\text{C}$

#### Notes:

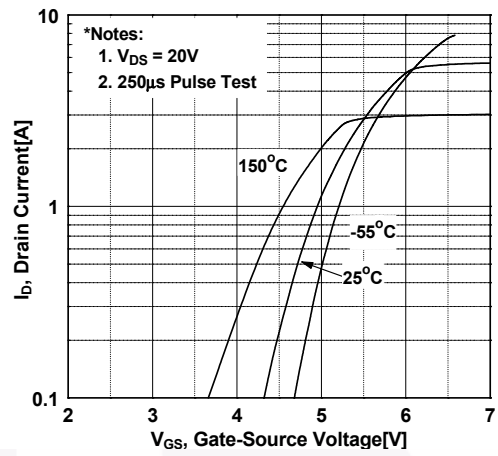
1. Repetitive rating: pulse width limited by maximum junction temperature.
2.  $I_{AS} = 0.52\text{ A}, R_G = 25\text{ }\Omega$ , starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 3.5\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , starting  $T_J = 25^\circ\text{C}$
4. Essentially independent of operating temperature typical characteristic.

## Typical Performance Characteristics

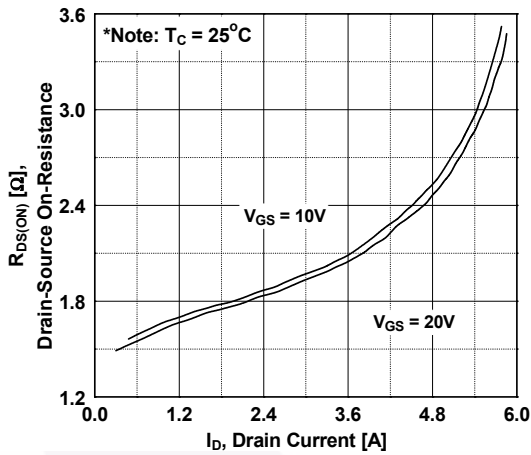
**Figure 1. On-Region Characteristics**



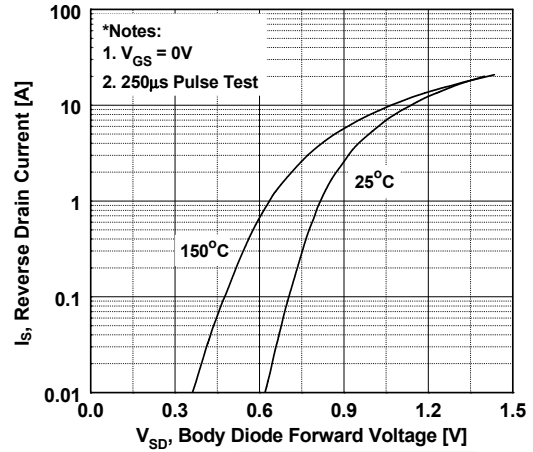
**Figure 2. Transfer Characteristics**



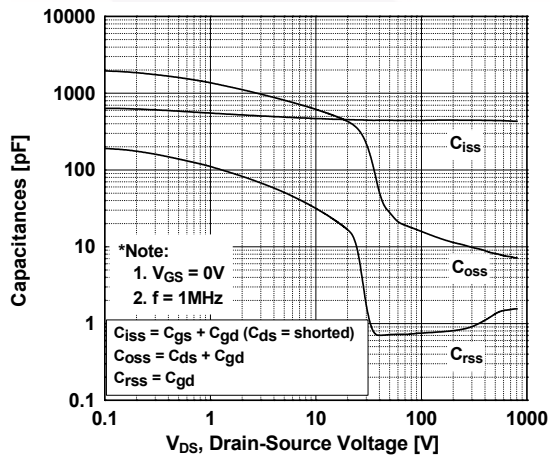
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



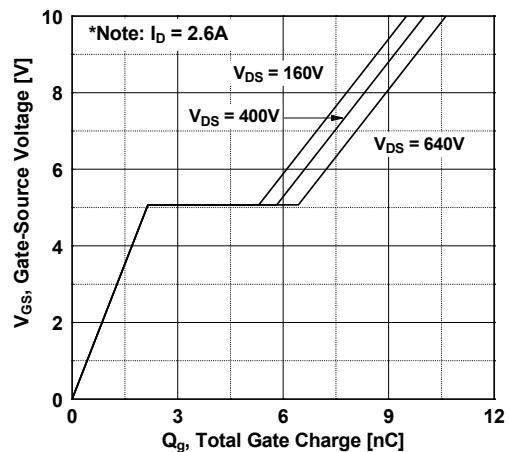
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

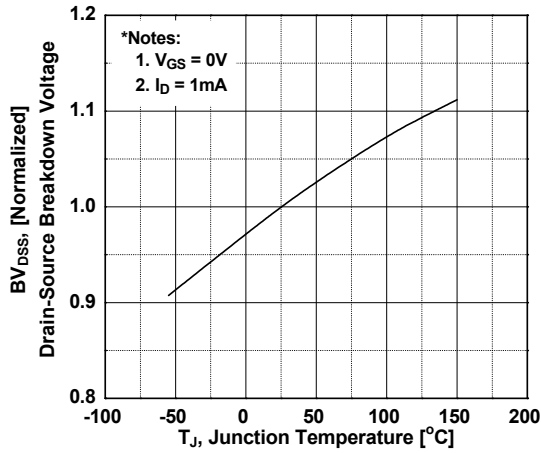


**Figure 6. Gate Charge Characteristics**

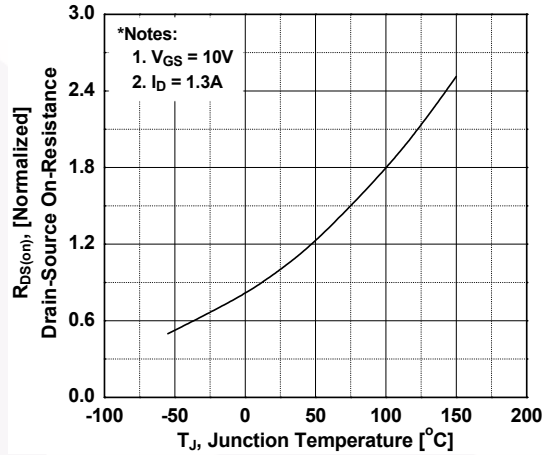


**Typical Performance Characteristics** (Continued)

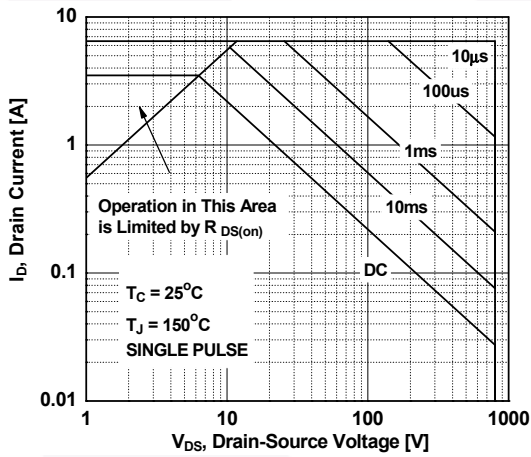
**Figure 7. Breakdown Voltage Variation vs. Temperature**



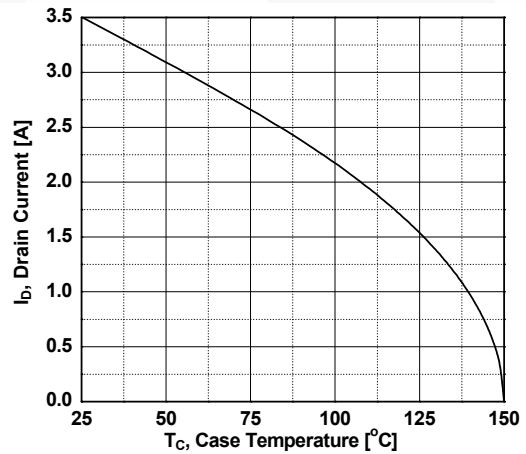
**Figure 8. On-Resistance Variation vs. Temperature**



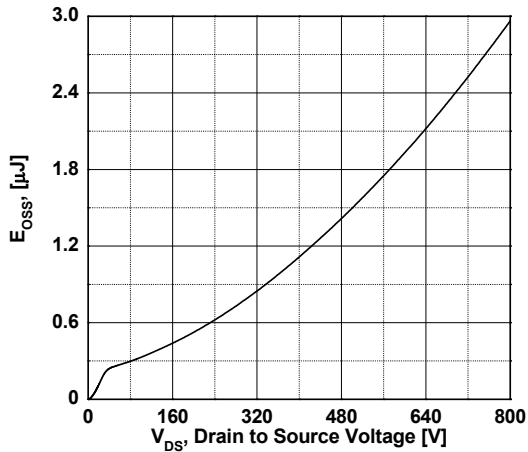
**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**

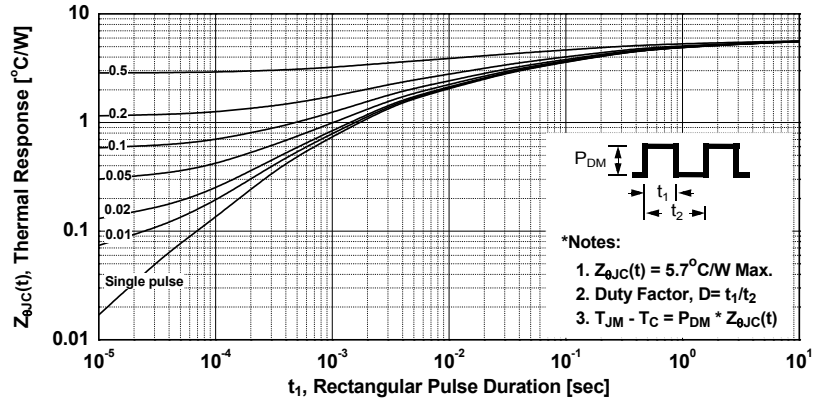


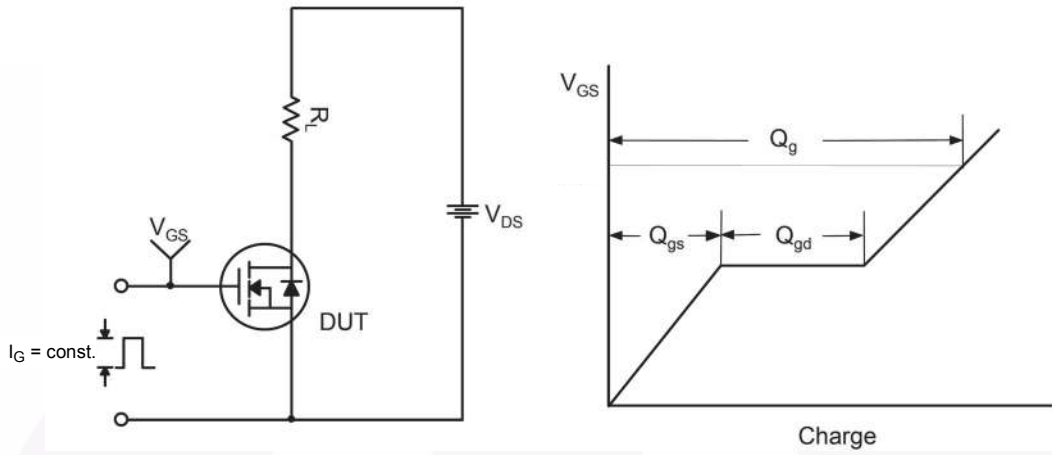
**Figure 11. E\_oss vs. Drain to Source Voltage**



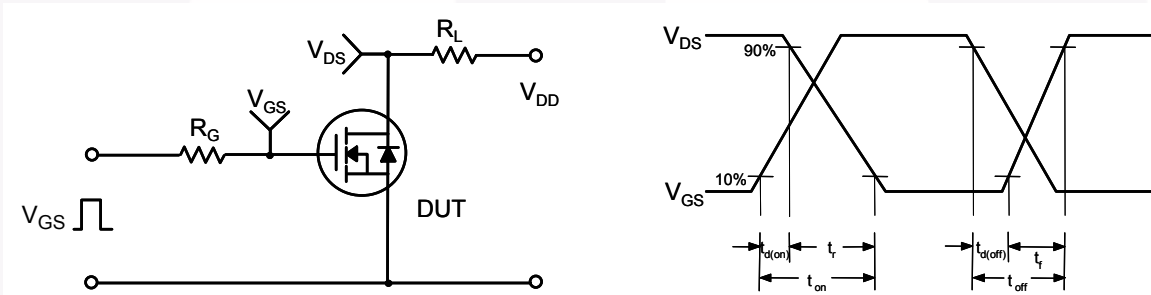
Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve

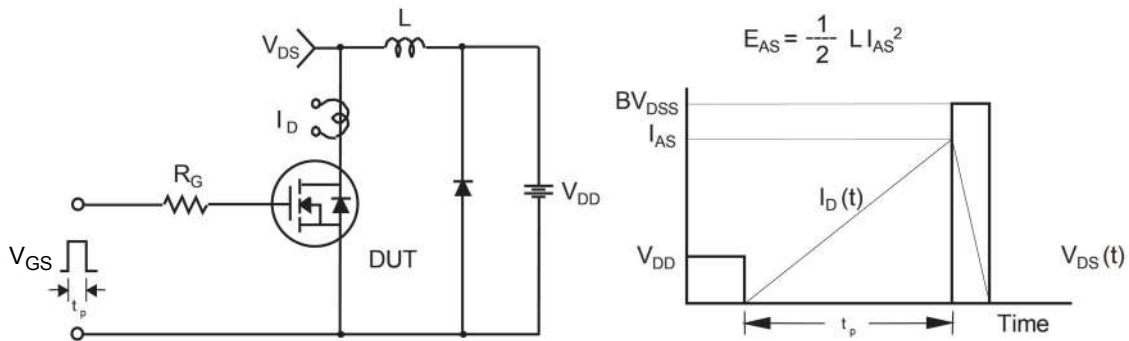




**Figure 13. Gate Charge Test Circuit & Waveform**



**Figure 14. Resistive Switching Test Circuit & Waveforms**



**Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms**

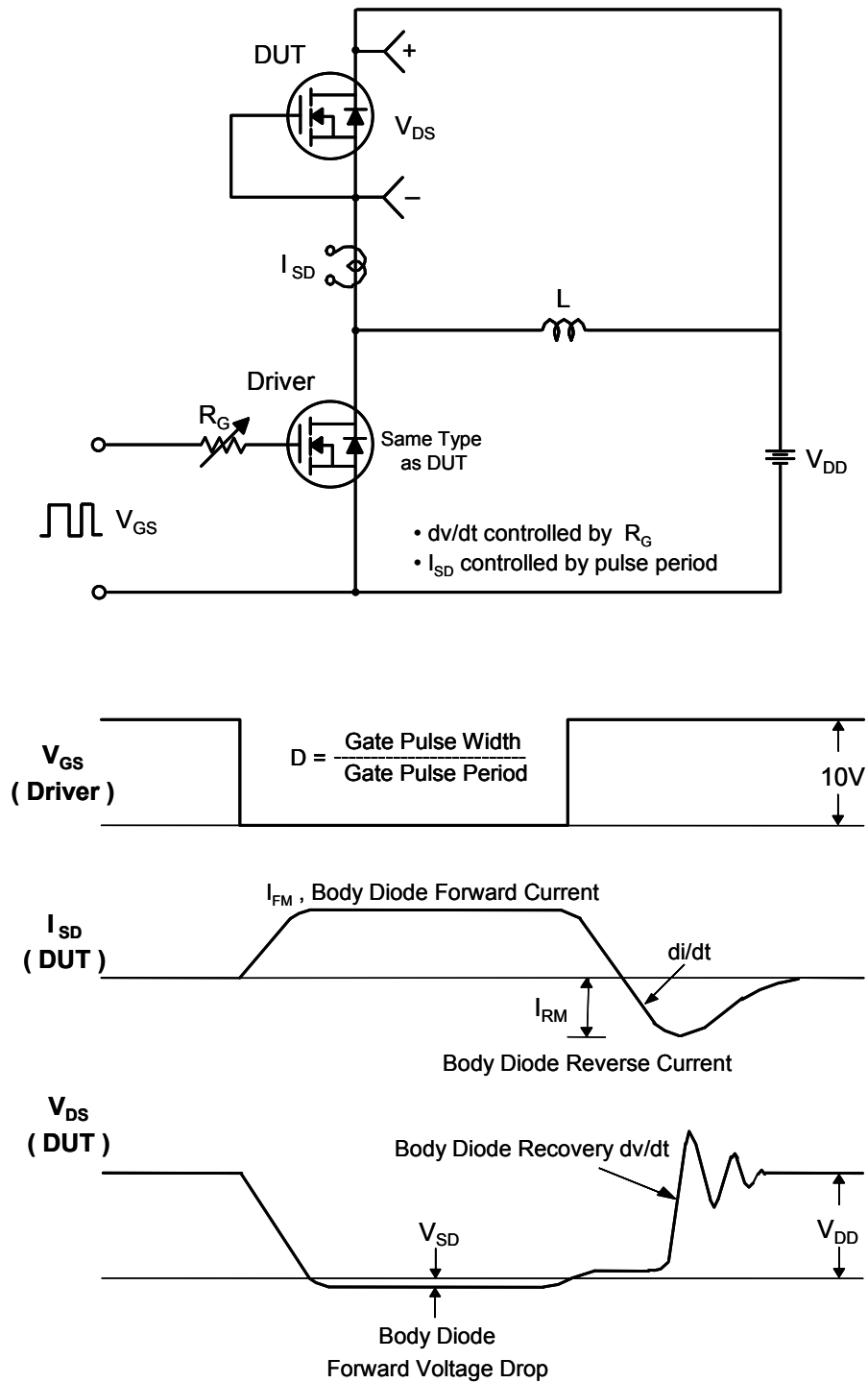
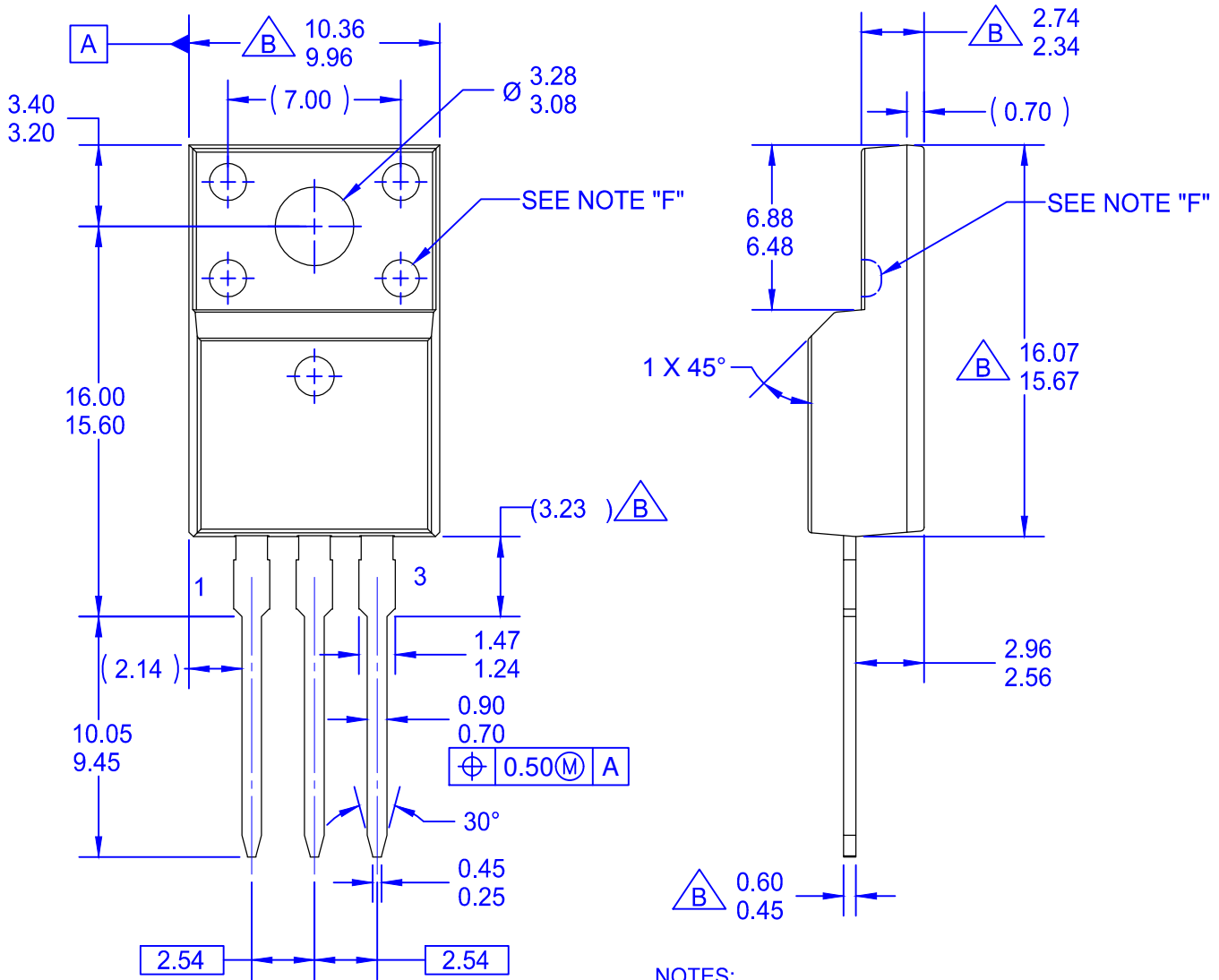


Figure 16. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms



NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
- B. DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. OPTION 1 - WITH SUPPORT PIN HOLE.  
OPTION 2 - NO SUPPORT PIN HOLE.
- G. DRAWING FILE NAME: TO220M03REV4









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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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